

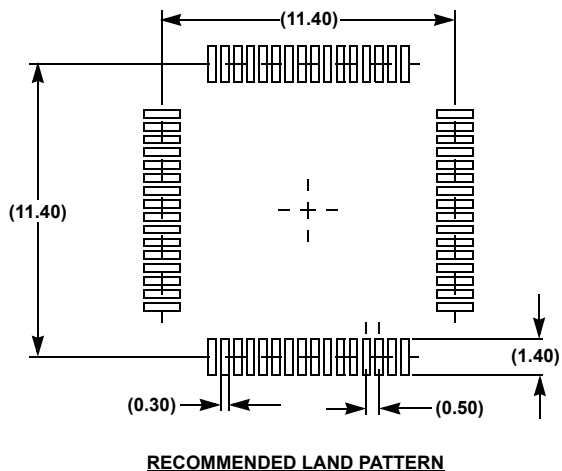
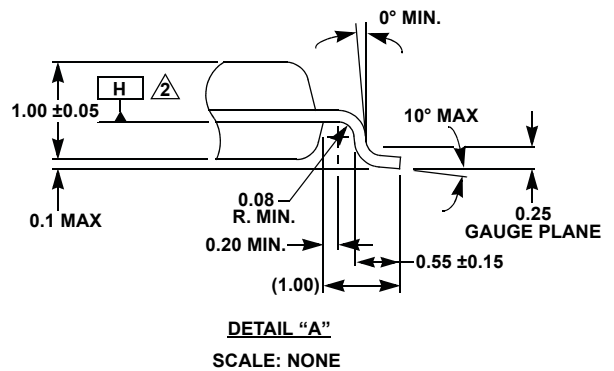
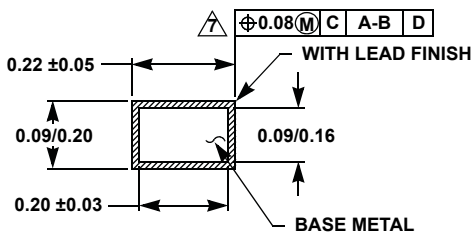
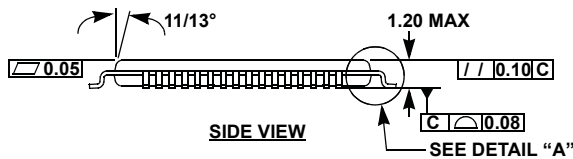
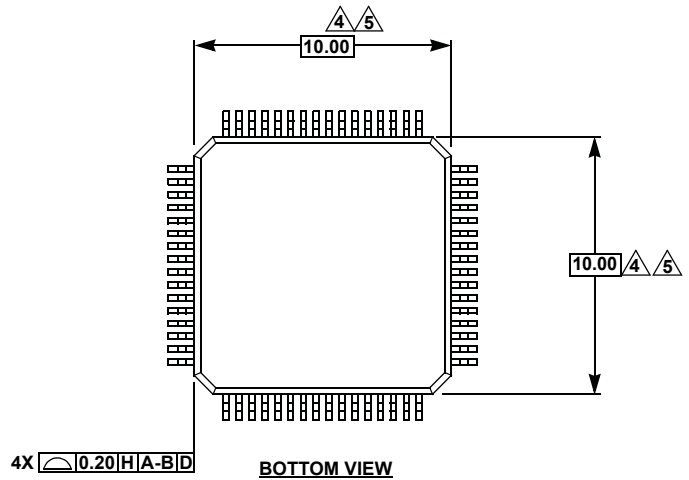
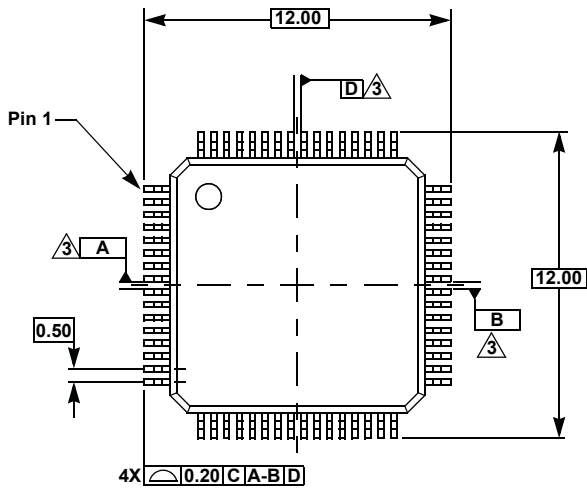
Plastic Packages for Integrated Circuits

Package Outline Drawing

Q64.10x10K

64 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE

Rev 0, 10/16



NOTES:

- All dimensioning and tolerancing conform to ANSI Y14.5-1982.
- Datum Plane [H] located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- Datums [A-B] and [D] to be determined at centerline between leads where leads exit plastic body at datum Plane [H].
- Dimensions do not include mold protrusion. Allowable mold protrusion is 0.254mm dimensions.
- These dimensions to be determined at datum Plane [H].
- Package top dimensions are smaller than bottom dimensions and top of package will not overhang bottom of package.
- Does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm total at maximum material condition. Dambar cannot be located on the lower radius or the foot.
- Controlling dimension: millimeter. This outline conforms to JEDEC Publication 95.
- Registration MS-026, variation ACD.
- Dimensions in () are for reference only.